

ABSTRACT

Provided is a novel anode for electroplating, which replaces the Cu anode and which is capable of suppressing plating defects. The Co anode has a number of particles with a grain size of 0.5 μm or more of 6000 particles/g or less, as measured by an in-liquid particle counter according to JIS B 9925 after dissolving the Co anode in dilute nitric acid having a nitric acid concentration of 20% by mass.